

Power MOSFET

PRODUCT SUMMARY		
V_{DS} (V)	60	
$R_{DS(on)}$ (Ω)	$V_{GS} = 5.0$ V	0.20
Q_g (Max.) (nC)	8.4	
Q_{gs} (nC)	3.5	
Q_{gd} (nC)	6.0	
Configuration	Single	

FEATURES

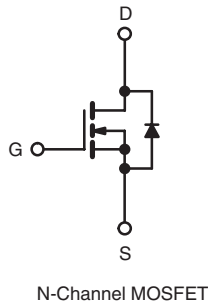
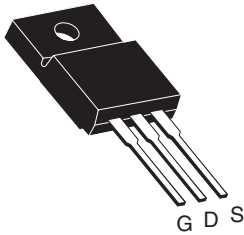
- Isolated Package
- High Voltage Isolation = 2.5 kV_{RMS} (t = 60 s; f = 60 Hz)
- Sink to Lead Creepage Distance = 4.8 mm
- Logic-Level Gate Drive
- $R_{DS(on)}$ Specified at $V_{GS} = 4$ V and 5 V
- Fast Switching
- Ease of Paralleling
- Lead (Pb)-free Available


 Available
RoHS*
 COMPLIANT

DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220 FULLPAK eliminates the need for additional insulating hardware in commercial-industrial applications. The molding compound used provides a high isolation capability and a low thermal resistance between the tab and external heatsink. This isolation is equivalent to using a 100 micron mica barrier with standard TO-220 product. The FULLPAK is mounted to a heatsink using a single clip or by a single screw fixing.

TO-220 FULLPAK


ORDERING INFORMATION

Package	TO-220 FULLPAK
Lead (Pb)-free	IRLIZ14GPbF
	SiHLIZ14G-E3
SnPb	IRLIZ14G
	SiHLIZ14G

ABSOLUTE MAXIMUM RATINGS $T_C = 25$ °C, unless otherwise noted

PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-Source Voltage	V_{DS}	60	V	
Gate-Source Voltage	V_{GS}	± 10		
Continuous Drain Current	V_{GS} at 5.0 V	$T_C = 25$ °C	8.0	A
		$T_C = 100$ °C		
Pulsed Drain Current ^a		I_{DM}	32	
Linear Derating Factor			0.18	W/°C
Single Pulse Avalanche Energy ^b		E_{AS}	68	mJ
Maximum Power Dissipation	$T_C = 25$ °C	P_D	27	W
Peak Diode Recovery dV/dt ^c		dV/dt	4.5	V/ns
Operating Junction and Storage Temperature Range		T_J, T_{stg}	- 55 to + 175	°C
Soldering Recommendations (Peak Temperature)	for 10 s		300 ^d	
Mounting Torque	6-32 or M3 screw		10	
			1.1	N · m

Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- $V_{DD} = 25$ V, starting $T_J = 25$ °C, L = 1.2 mH, $R_G = 25$ Ω , $I_{AS} = 8.0$ A (see fig. 12).
- $I_{SD} \leq 10$ A, $dI/dt \leq 90$ A/ μ s, $V_{DD} \leq V_{DS}$, $T_J \leq 175$ °C.
- 1.6 mm from case.

* Pb containing terminations are not RoHS compliant, exemptions may apply

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	65	°C/W
Maximum Junction-to-Case (Drain)	R_{thJC}	-	5.5	

SPECIFICATIONS $T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$		60	-	-	V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to $25\text{ }^\circ\text{C}, I_D = 1\text{ mA}$		-	0.070	-	V/°C
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$		1.0	-	2.0	V
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 10\text{ V}$		-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 60\text{ V}, V_{GS} = 0\text{ V}$		-	-	25	μA
		$V_{DS} = 48\text{ V}, V_{GS} = 0\text{ V}, T_J = 150\text{ }^\circ\text{C}$		-	-	250	
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 5.0\text{ V}$	$I_D = 4.8\text{ A}^b$	-	-	0.20	Ω
		$V_{GS} = 4.0\text{ V}$	$I_D = 4.0\text{ A}^b$	-	-	0.28	
Forward Transconductance	g_{fs}	$V_{DS} = 25\text{ V}, I_D = 4.8\text{ A}^b$		3.6	-	-	S
Dynamic							
Input Capacitance	C_{iss}	$V_{GS} = 0\text{ V},$ $V_{DS} = 25\text{ V},$ $f = 1.0\text{ MHz},$ see fig. 5		-	400	-	pF
Output Capacitance	C_{oss}			-	170	-	
Reverse Transfer Capacitance	C_{riss}			-	42	-	
Drain to Sink Capacitance	C	$f = 1.0\text{ MHz}$		-	12	-	
Total Gate Charge	Q_g	$V_{GS} = 5.0\text{ V}$	$I_D = 10\text{ A}, V_{DS} = 48\text{ V},$ see fig. 6 and 13 ^b	-	-	8.4	nC
Gate-Source Charge	Q_{gs}			-	-	3.5	
Gate-Drain Charge	Q_{gd}			-	-	6.0	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 30\text{ V}, I_D = 10\text{ A},$ $R_G = 12\text{ }\Omega, R_D = 2.8\text{ }\Omega,$ see fig. 10 ^b		-	9.3	-	ns
Rise Time	t_r			-	110	-	
Turn-Off Delay Time	$t_{d(off)}$			-	17	-	
Fall Time	t_f			-	26	-	
Internal Drain Inductance	L_D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	nH
Internal Source Inductance	L_S			-	7.5	-	
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	8.0	A
Pulsed Diode Forward Current ^a	I_{SM}			-	-	32	
Body Diode Voltage	V_{SD}	$T_J = 25\text{ }^\circ\text{C}, I_S = 8.0\text{ A}, V_{GS} = 0\text{ V}^b$		-	-	1.6	V
Body Diode Reverse Recovery Time	t_{rr}	$T_J = 25\text{ }^\circ\text{C}, I_F = 10\text{ A}, dI/dt = 100\text{ A}/\mu\text{s}^b$		-	65	130	ns
Body Diode Reverse Recovery Charge	Q_{rr}			-	0.33	0.65	μC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)					

Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- Pulse width $\leq 300\text{ }\mu\text{s}$; duty cycle $\leq 2\%$.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

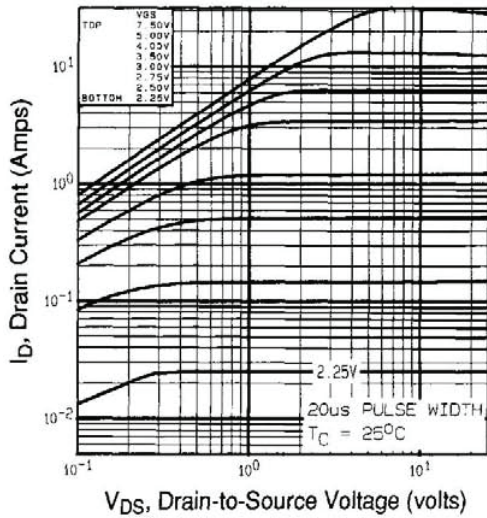


Fig. 1 - Typical Output Characteristics, $T_C = 25\text{ }^\circ\text{C}$

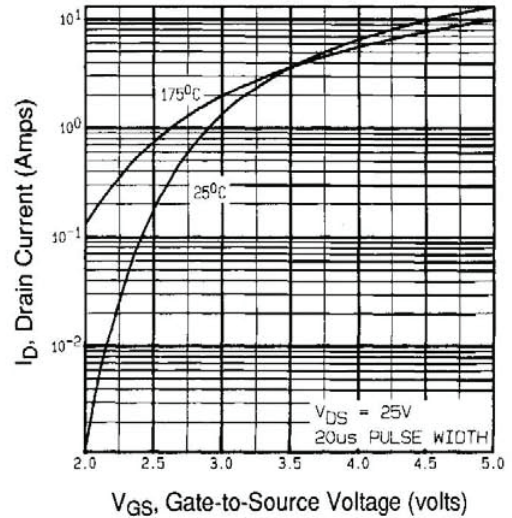


Fig. 3 - Typical Transfer Characteristics

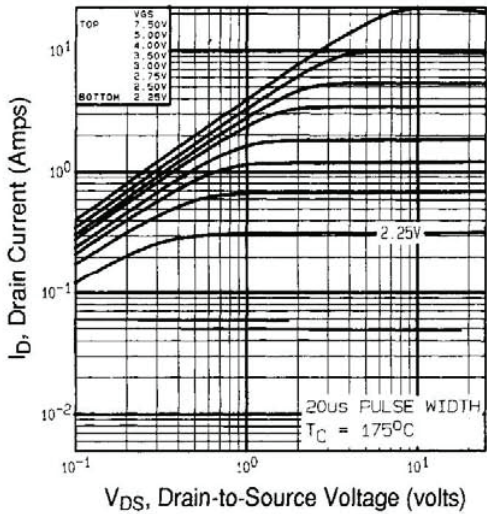


Fig. 2 - Typical Output Characteristics, $T_C = 175\text{ }^\circ\text{C}$

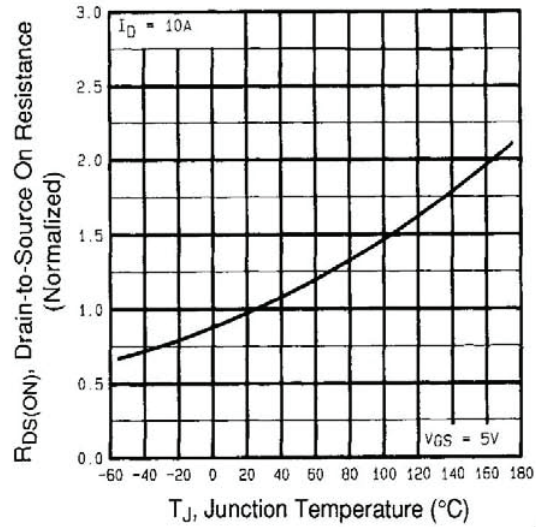


Fig. 4 - Normalized On-Resistance vs. Temperature

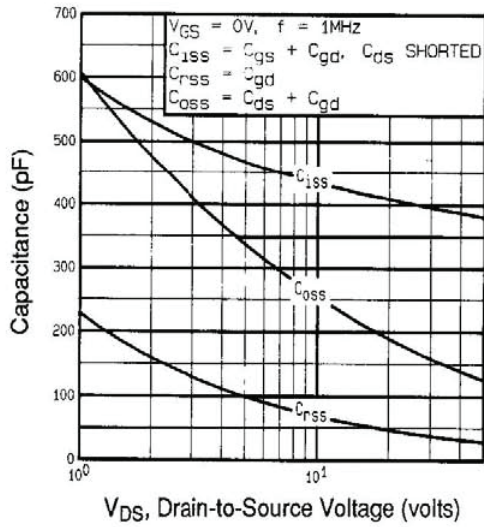


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

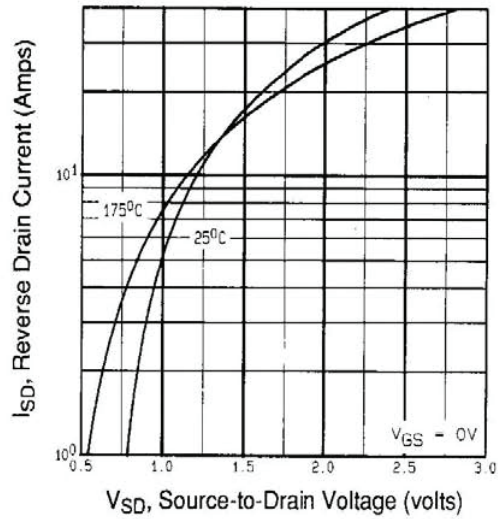


Fig. 7 - Typical Source-Drain Diode Forward Voltage

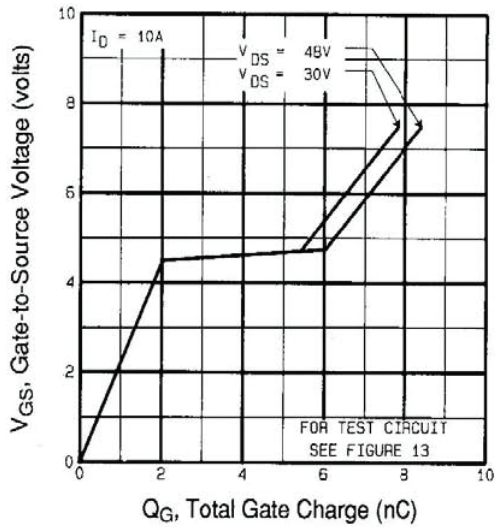


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

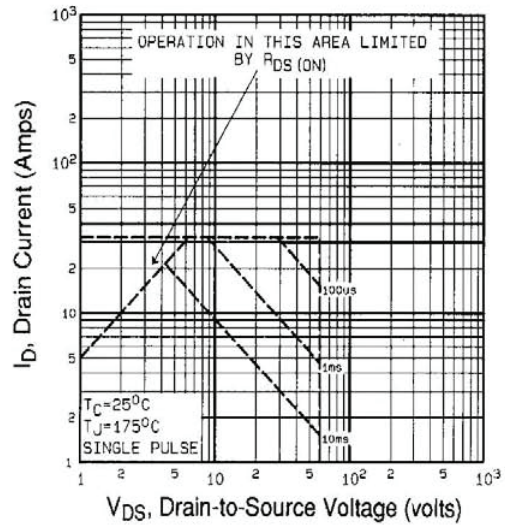


Fig. 8 - Maximum Safe Operating Area

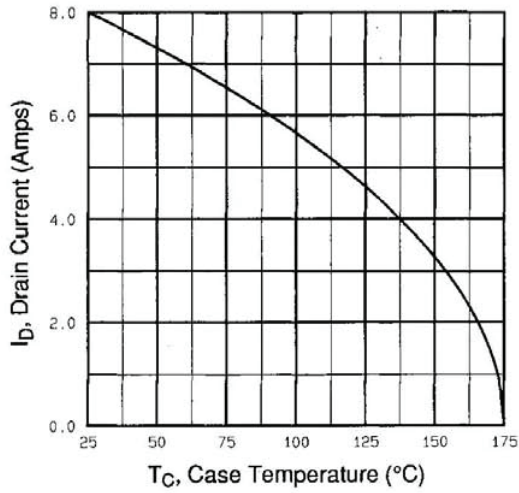


Fig. 9 - Maximum Drain Current vs. Case Temperature

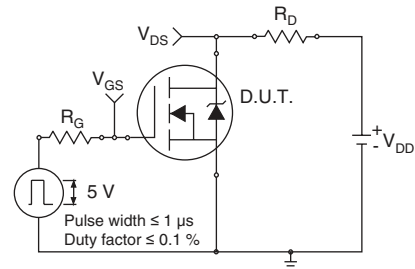


Fig. 10a - Switching Time Test Circuit



Fig. 10b - Switching Time Waveforms

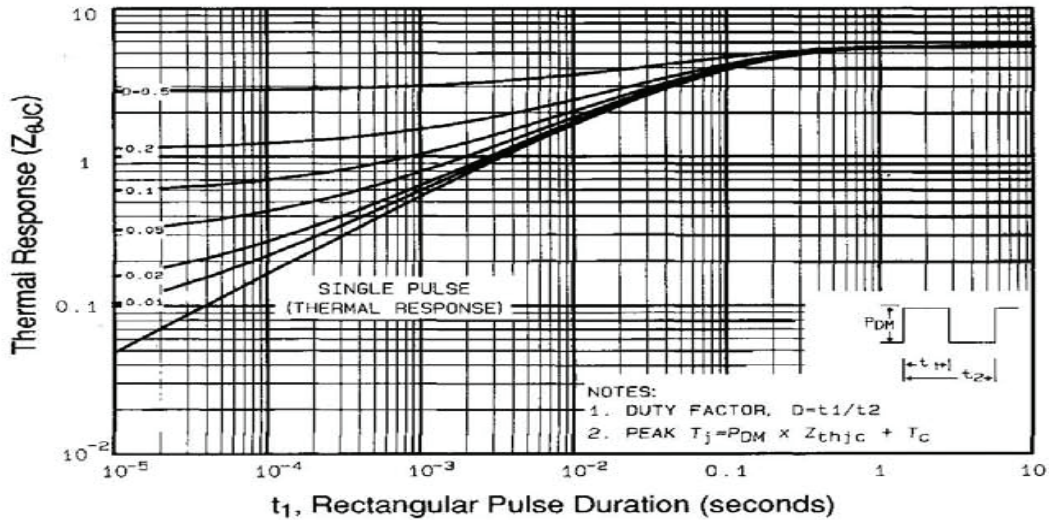


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

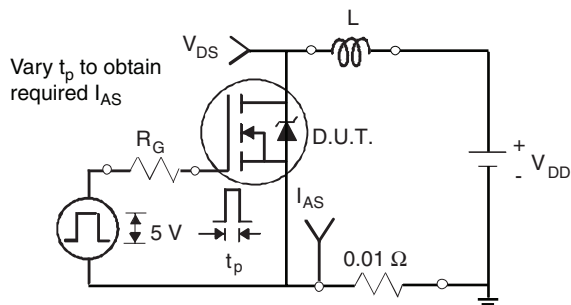


Fig. 12a - Unclamped Inductive Test Circuit

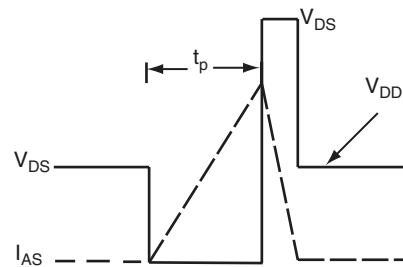


Fig. 12b - Unclamped Inductive Waveforms

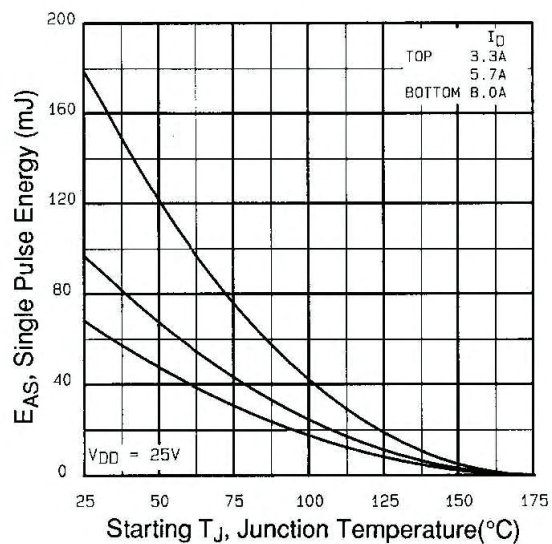


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

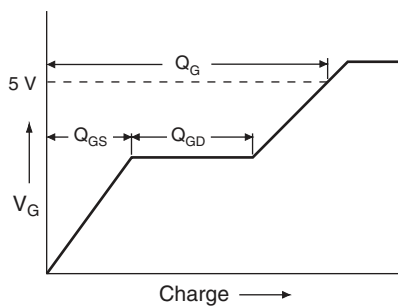


Fig. 13a - Basic Gate Charge Waveform

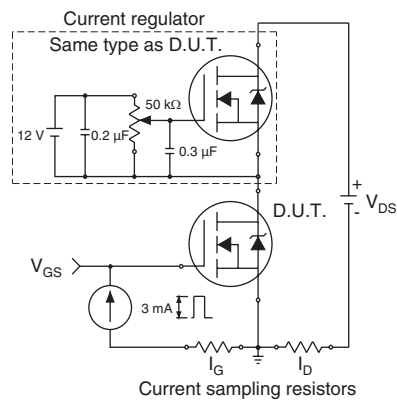
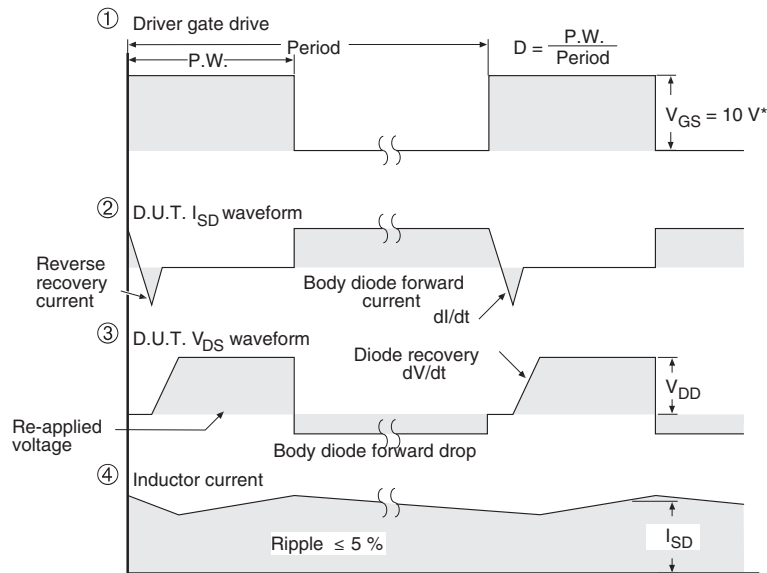
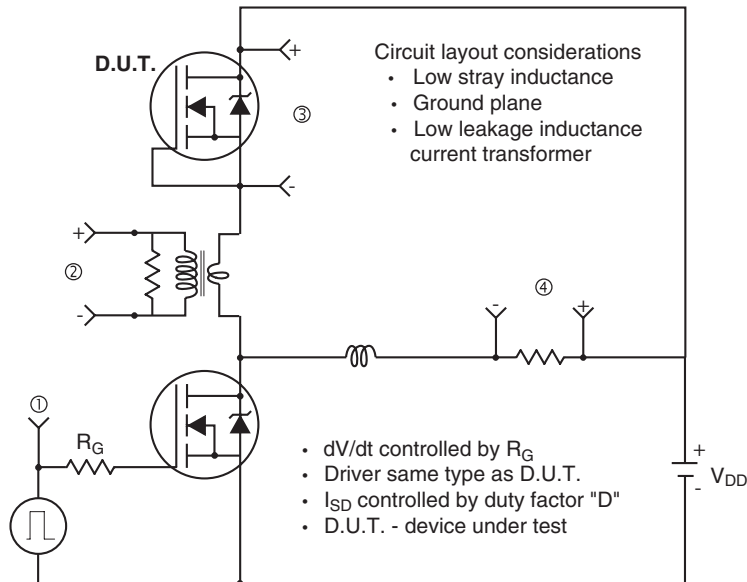


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



* $V_{GS} = 5\text{ V}$ for logic level devices and 3 V drive devices

Fig. 14 - For N-Channel

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